



Differential, Compensated Pressure Sensor (0 to 40 kPa)

MPX230xDT1

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The MPX230xDT1 offers a cost-effective, high-volume miniature pressure sensor package targeting medical applications.

- Provides an ideal solution for sub-module components or disposable units
- Uses our sensor die with its piezoresistive technology along with the added feature of on-chip, thin-film temperature compensation and calibration
- Enables flexibility and cost savings in system designs

MPX230XDT1_BD Block Diagram

PACKAGING ORDERING INFORMATION

Device Type	Packing Options	Case
MPX2300DT1	Chip Pak, Full Gel	423A
MPX2301DT1	Chip Pak, 1/3 Gel	423A

View additional information for [Differential, Compensated Pressure Sensor \(0 to 40 kPa\)](#).

Note: The information on this document is subject to change without notice.

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